

L Number	Hits	Search Text	DB	Time stamp
1	8	wafer and (undoped with silicon) same etch\$ and 29/\$.ccls.	USPAT	2002/06/08 11:20
-	179	chang-rick-kiltae.xa.	USPAT	2002/06/07 12:16
-	38	("3275736" "3670409" "3818415" "3823467" "3937386" "3998377" "4067104" "4189825" "4655519" "4695870" "4716049" "4846704" "4893172" "4902606" "4924353" "4950173" "4950623" "4955523" "4975079" "5006792" "5067007" "5086337" "5130768" "5152695" "5173055" "5181859" "5196726" "5199879" "5214308" "5228861" "5311402" "5349495" "5354205" "5360347" "5380210" "5455390" "5632631" "5802699").PN.	USPAT	2002/06/06 12:00
-	43	("3256589" "3275736" "3670409" "3818415" "3823467" "3937386" "3998377" "4067104" "4189825" "4205889" "4655519" "4695870" "4716049" "4846704" "4893172" "4902606" "4924353" "4950173" "4950623" "4955523" "4975079" "5006792" "5067007" "5086337" "5130768" "5152695" "5173055" "5181859" "5196726" "5199879" "5214308" "5224264" "5228861" "5311402" "5349495" "5354205" "5360347" "5380210" "5455390" "5481798" "5525545" "5632631" "5722159").PN.	USPAT	2002/06/06 12:07
-	1	5802699.pn. and etch\$	USPAT	2002/06/07 06:15
-	1	29/825.ccls. and demarcat\$	USPAT	2002/06/07 06:16
-	1	29/846.ccls. and demarcat\$	USPAT	2002/06/07 06:17
-	173	29/846.ccls. and carrier	USPAT	2002/06/07 06:29
-	3	439/\$.ccls. and wafer and (undoped same silicon)	USPAT	2002/06/07 06:38
-	339	439/82.ccls.	USPAT	2002/06/07 07:29
-	24	439/82.ccls. and etch\$	USPAT	2002/06/07 07:42
-	0	"09693484"	US-PGPUB	2002/06/07 07:42
-	71	29/846.ccls.	US-PGPUB	2002/06/07 07:47
-	36	439/66.ccls.	US-PGPUB	2002/06/07 07:47
-	631	439/66.ccls.	USPAT	2002/06/07 10:56
-	20	439/66.ccls. and suspens\$	USPAT	2002/06/07 07:57
-	11	439/70,71,72.ccls. and suspens\$	USPAT	2002/06/07 07:58
-	0	439/66.ccls. and wafer and (undoped same silicon)	USPAT	2002/06/07 10:56
-	0	439/66.ccls. and (undoped same silicon)	USPAT	2002/06/07 12:56
-	118	439/66.ccls. and silicon	USPAT	2002/06/07 12:12
-	82	29/848.ccls. and mold\$	USPAT	2002/06/07 12:18
-	179	chang-rick-kiltae.xa.	USPAT	2002/06/07 12:16
-	44	29/848.ccls. and mold\$ and cur\$	USPAT	2002/06/07 12:56
-	4047	undoped with silicon	USPAT	2002/06/07 12:58
-	2	(undoped with silicon) same etch\$ and 439/\$.ccls.	USPAT	2002/06/07 13:01
-	10	(undoped with silicon) same etch\$ and 29/\$.ccls.	USPAT	2002/06/08 11:20